

59/639283

## ABSTRACT

An integrated circuit die carries conductive pads and thereon, the larger pads being suitable for flip-chip assembly and the smaller pads being suitable for wire bond assembly. The pitch between pads is at least the minimum required for flip-chip  
5 assembly, whereas the pitch between each of pads and the adjacent pad or pads is at least the minimum required for wire bond assembly. For wire bond assembly a passivation layer exposing all pads is provided, whereas for flip-chip assembly a passivation layer exposes only certain pads so that conductive bumps may be provided. The provision of  
10 pads complying with the minimum spacing requirements for both flip-chip and wire bond assembly enables a "dual purpose" (e.g. one set of pads being for normal production and another set for testing purposes) die to be produced without any increase in die size.

005150-888888